

Data sheet

SAW RF filter
Automotive telematics
TD-LTE band 41

Part number: B2656

Ordering code: B39262B2656P810

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1 Application

- Band 41 (full band) Rx filter for 4G and 5G application.
- TD-LTE band 41: 2593 MHz (pass band 194 MHz)
- Low insertion loss and high WiFi rejection.
- Unbalanced to unbalanced operation.

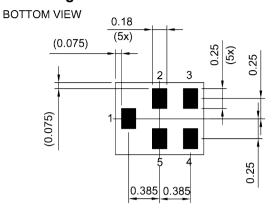
2 Features

- Package size 1.1±0.1 mm × 0.9±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family (Grade 1: -40 °C to +125 °C)



Figure 1: Picture of component with example of product marking.

3 Package



Pad and pitch tolerance ±0.05

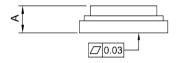
4 Pin configuration

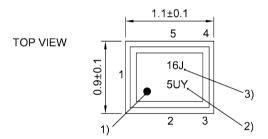
■ 1 Input

■ 4 Output

■ 2, 3, 5 Ground

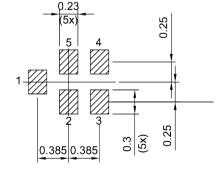
SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



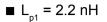


Landing pad tolerance -0.02

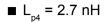
Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 20).



5 Matching circuit



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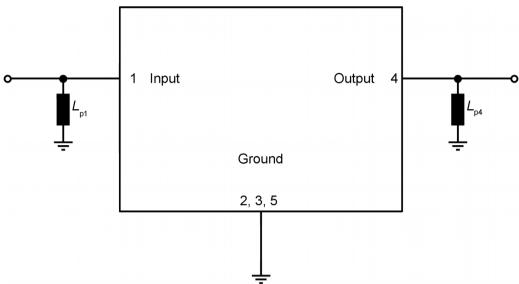


Figure 3: Schematic of matching circuit.



6 Characteristics

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Temperature range for specification $T_{\rm SPEC}$ Input terminating impedance $Z_{\rm IN}$ Output terminating impedance $Z_{\rm CUT}$

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f _C	_	2593	_	MHz
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	2496 2690	MHz		_	2.0	2.5 ²⁾	dB
	2496 2690	MHz		_	2.0	2.8	dB
Amplitude ripple (p-p)			Δα				
	2496 2690	MHz		_	1.0	1.72)	dB
	2496 2690	MHz		_	1.0	1.9	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	2496 2690	MHz		_	1.4	2.0	
@ output port	2496 2690	MHz		_	1.7	2.2	
Average attenuation			$\alpha_{\text{WLAN,avg}}^{\qquad 3)}$				
Wi-fi Channel 1	2403 2421	MHz		30	33	_	dB
Wi-fi Channel 2	2408 2426	MHz		30	33	_	dB
Wi-fi Channel 3	2413 2431	MHz		30	33	_	dB
Wi-fi Channel 4	2418 2436	MHz		30	33	_	dB
Wi-fi Channel 5	2423 2441	MHz		30	34	_	dB
Wi-fi Channel 6	2428 2446	MHz		30	34	_	dB
Wi-fi Channel 7	2433 2451	MHz		30	35	_	dB
Wi-fi Channel 8	2438 2456	MHz		30	37	_	dB
Wi-fi Channel 9	2443 2461	MHz		25	39	_	dB
Wi-fi Channel 10	2448 2466	MHz		20	40	_	dB
Wi-fi Channel 11	2453 2471	MHz		10	40	_	dB
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	600 960	MHz		35	56	_	dB
	1166.22 1186.68	MHz		35	50	_	dB
	1248 1345	MHz		35	47	_	dB
	1427.9 1447.9	MHz		35	45	_	dB
	1559.05 1605.89	MHz		31	41	_	dB
	1710 1785	MHz		35	39	_	dB
	1850 1920	MHz		30	38	_	dB
	1920 1980	MHz		35	39	_	dB
	2750 2775	MHz		10	26	_	dB
	3300 3550	MHz		32	37	_	dB
	3550 3700	MHz		27	31	_	dB
	3700 4200	MHz		30	33	_	dB
	4400 5000	MHz		29	31	_	dB

= -30 °C ... +85 °C

= 50 Ω // 2.2 $nH^{1)}$

= 50 Ω // 2.7 nH¹⁾



Characteristics		$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
4992 5380	MHz	27	30	_	dB
5150 5850	MHz	25	29	_	dB
5925 7125	MHz	25	27	_	dB
7488 8070	MHz	20	25	_	dB

See Sec. Matching circuit (p. 6).

Valid for typical temperature T = +25 °C.

³⁾ Average over each WLAN channel with band width of 18 MHz.



7 Maximum ratings

Operable temperature	T _{OP} = −40 °C +125 °C	
Storage temperature	T _{STG} ¹⁾ = −40 °C +125 °C	
DC voltage	$ V_{DC} ^{2} = 0 \text{ V (max.)}$	
@ input port: 2496 2690 MHz Input power	P _{IN} = 15 dBm	Continuous wave for 5000 h @ 50 °C.

Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

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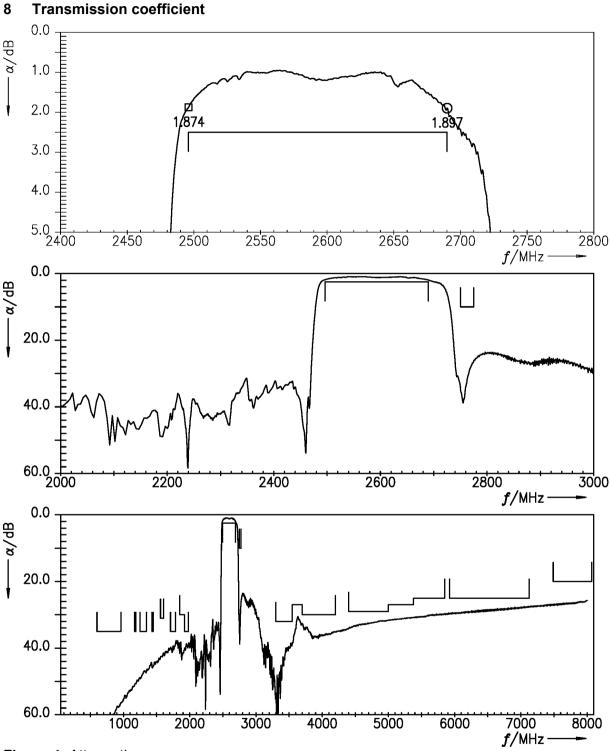


Figure 4: Attenuation.

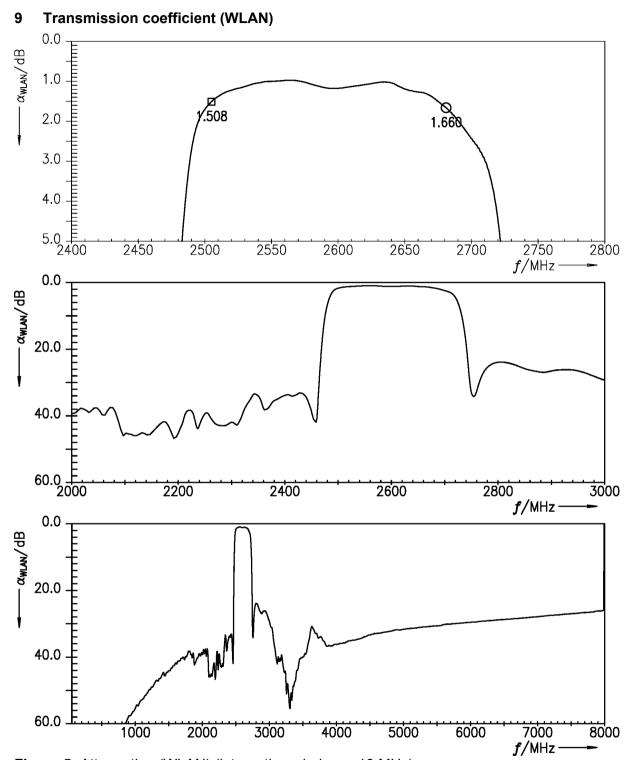
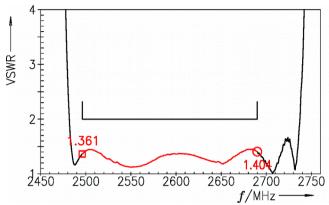


Figure 5: Attenuation (WLAN) (integration window = 18 MHz).



10 Reflection coefficients



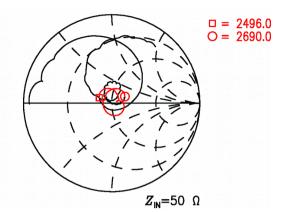
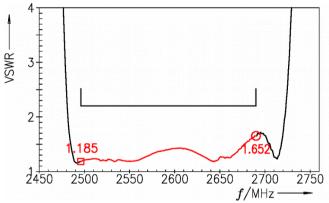


Figure 6: Reflection coefficient at input port.



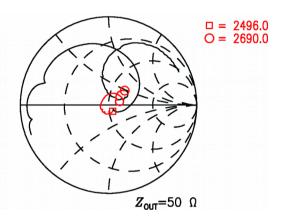


Figure 7: Reflection coefficient at output port.



11 Packing material

11.1 Tape

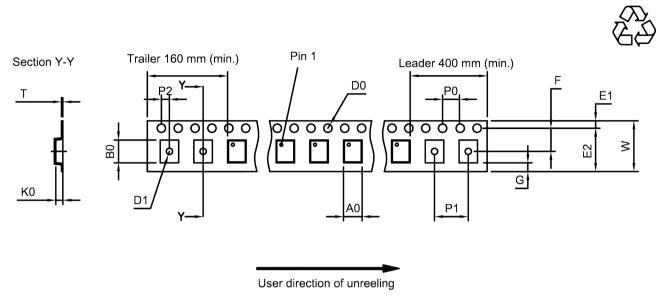


Figure 8: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.02±0.05 mm	_	E ₂	6.25 mm (min.)	_	P ₁	2.0±0.1 mm
B ₀	1.22±0.05 mm		F	3.5±0.05 mm		P_2	2.0±0.05 mm
D_0	1.55±0.05 mm		O	_		Т	0.25±0.03 mm
D ₁	0.55±0.1 mm		K ₀	0.6±0.05 mm	_	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	_	Po	4.0±0.1 mm	_		

Table 1: Tape dimensions.

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11.2 Reel with diameter of 180 mm

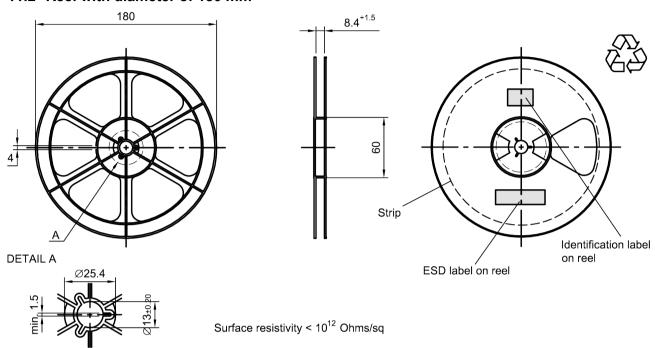


Figure 9: Drawing of reel (first-angle projection) with diameter of 180 mm.

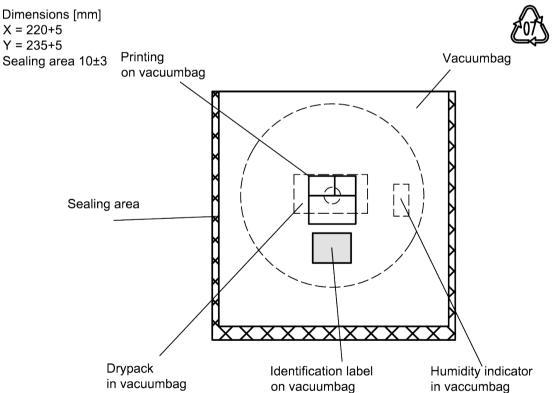


Figure 10: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

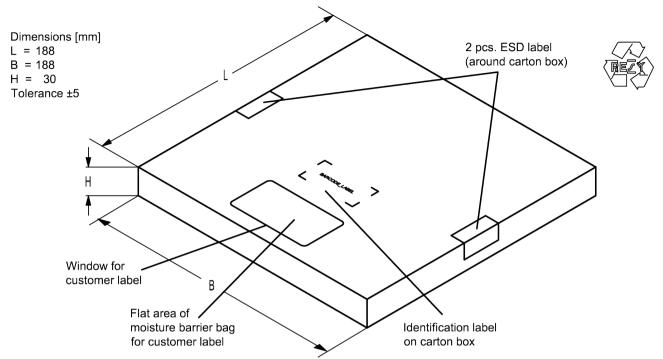


Figure 11: Drawing of folding box for reel with diameter of 180 mm.



12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB1234xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x 32^2 + 6 x 32^1 + 18 (=J) x 32^0 = 1234

The BASE32 code for product type B2656 is 2K0.

■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345 5 x 47² + 27 (=U) x 47¹ + 31 (=Y) x 47⁰ = 12345

Adopted BASE32 code for type number						
Decimal	Base32	Decimal	Base32			
value	code	value	code			
0	0	16	G			
1	1	17	Н			
2	2	18	J			
3	3	19	K			
4	4	20	M			
5	5	21	N			
6	6	22	Р			
7	7	23	Q			
8	8	24	R			
9	9	25	S			
10	Α	26	Т			
11	В	27	V			
12	С	28	W			
13	D	29	Х			
14	E	30	Y			
15	F	31	Z			

Adopted BASE47 code for lot number						
Decimal	Base47	Decimal	Base47			
value	code	value	code			
0	0	24	R			
1	1	25	S			
2	2	26	Т			
3	3	27	U			
4	4	28	V			
5	5	29	W			
6	6	30	X			
7	7	31	Y			
8	8	32	Z			
9	9	33	b			
10	Α	34	d			
11	В	35	f			
12	С	36	h			
13	D	37	n			
14	E	38	r			
15	F	39	t			
16	G	40	V			
17	Н	41	\			
18	J	42	?			
19	K	43	{			
20	L	44	}			
21	М	45	<			
22	N	46	>			
23	Р					

Table 2: Lists for encoding and decoding of marking.



13 Soldering profile

The recommended soldering process is in accordance with IEC $60068-2-58-3^{rd}$ edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

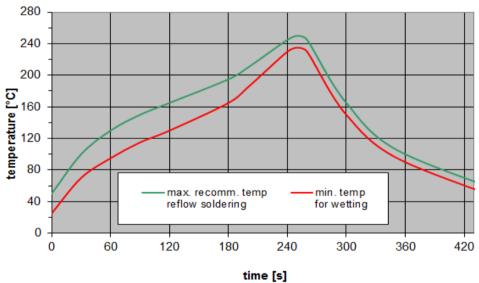


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.



14 ESD protection of acoustic devices

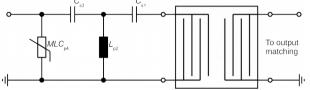
Acoustic devices are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies must be applied.

In general, "ESD matching" must be ensured at that electrical port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the acoustic device must be designed to short circuit or to block the ESD pulse.

Below three figures show recommended "ESD matching" topologies.

For wide band acoustic devices the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and input port. The required component values must be determined from case to case.



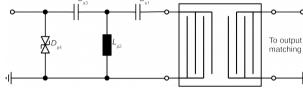


Figure 13: MLC varistor plus ESD matching.

Figure 14: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified "ESD matching" topologies can be used alternatively.

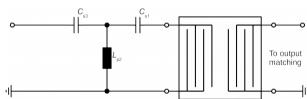


Figure 15: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: **"ESD protection for SAW filters".** This report can be found under https://rffe.qualcomm.com.



15 Annotations

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15.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

15.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.



16 Cautions and warnings

16.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.qualcomm.com/.

16.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

16.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

16.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.



17 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (https://rffe.qualcomm.com). Should you have any more detailed questions, please contact our sales offices.
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